

## General Description

The GreenMOS<sup>®</sup> high voltage MOSFET utilizes charge balance technology to achieve outstanding low on-resistance and lower gate charge. It is engineered to minimize conduction loss, provide superior switching performance and robust avalanche capability.

## Features

- 
- 
- 
- 

## Applications

- 
- 
- 
- 
- 



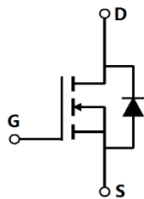

## Key Performance Parameters

Parameter	Value	Unit
$V_{DS, \min} @ T_{j(\max)}$	650	V
$I_D, \text{ pulse}$	90	A
$R_{DS(ON), \max} @ V_{GS}=10V$	108	
$Q_g$	37.1	nC

## Marking Information

Product Name	Package	Marking
OSG60R108FZF	TO220F	OSG60R108FZ

## Package & Pin Information



**Absolute Maximum Ratings** at  $T_j=25$  unless otherwise noted

Parameter	Symbol	Value	Unit
Drain-source voltage	$V_{DS}$	600	V
Gate-source voltage	$V_{GS}$	$\pm 30$	V
Continuous drain current <sup>1)</sup> , $T_C=25$ °C	$I_D$	30	A
Continuous drain current <sup>1)</sup> , $T_C=100$ °C		19	
Pulsed drain current <sup>2)</sup> , $T_C=25$ °C	$I_{D, pulse}$	90	A
Continuous diode forward current <sup>1)</sup> , $T_C=25$ °C	$I_S$	30	A
Diode pulsed current <sup>2)</sup> , $T_C=25$ °C	$I_{S, pulse}$	90	A
Power dissipation <sup>3)</sup> , $T_C=25$ °C	$P_D$	34	W
Single pulsed avalanche energy <sup>5)</sup>	$E_{AS}$	1000	mJ
MOSFET dv/dt ruggedness, $V_{DS}$	dv/dt	50	V/ns
Reverse diode dv/dt, $V_{DS}$	dv/dt	50	V/ns
Operation and storage temperature	$T_{stg}, T_j$	-55 to 150	°C

**Thermal Characteristics**

Parameter	Symbol	Value	Unit
Thermal resistance, junction-case	R	3.7	°C/W
Thermal resistance, junction-ambient <sup>4)</sup>	R	62.5	°C/W

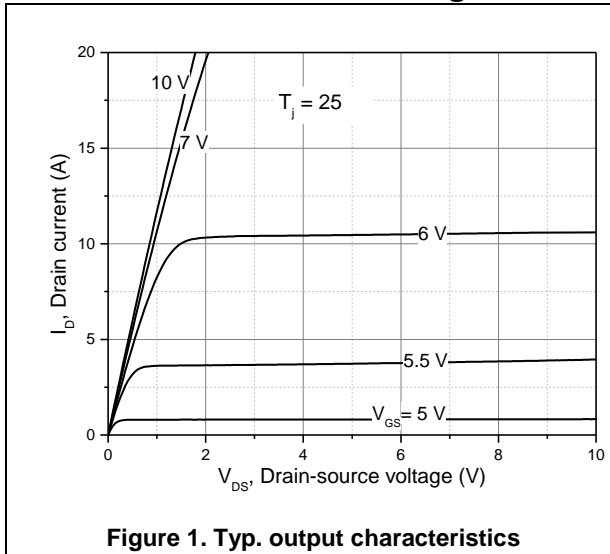
**Electrical Characteristics** at  $T_j=25$  unless otherwise specified

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Drain-source breakdown voltage	$BV_{DSS}$	600			V	$V_{GS}=0$ V, $I_D=1$ mA
		650				$V_{GS}=0$ V, $I_D=1$ mA, $T_j=150$ °C
Gate threshold voltage	$V_{GS(th)}$	3		4.5	V	$V_{DS}=V_{GS}$ , $I_D=1$ mA
Drain-source on-state resistance	$R_{DS(ON)}$		0.085	0.108		$V_{GS}=10$ V, $I_D=15$ A
			0.2			$V_{GS}=10$ V, $I_D=15$ A, $T_j=150$ °C
Gate-source leakage current	$I_{GSS}$			100	nA	$V_{GS}=30$ V
				-100		$V_{GS}=-30$ V
Drain-source leakage current	$I_{DSS}$			10	A	$V_{DS}=600$ V, $V_{GS}=0$ V

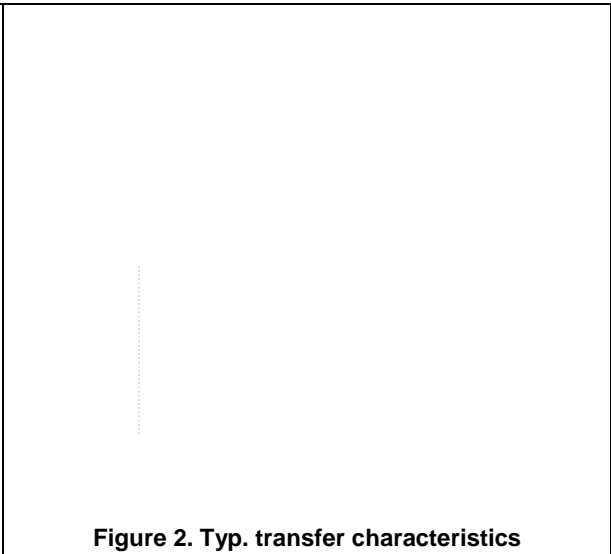
**Dynamic Characteristics**

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test condition
Input capacitance	$C_{iss}$		2674.5		pF	$V_{GS}=0\text{ V}$ , $V_{DS}=50\text{ V}$ , Hz
Output capacitance	$C_{oss}$		246.0		pF	
Reverse transfer capacitance	$C_{rss}$		9.6		pF	
Turn-on delay time	$t_{d(on)}$		67.4		ns	$V_{GS}=10\text{ V}$ , $V_{DS}=400\text{ V}$ , $R_G$ $I_D=16\text{ A}$
Rise time	$t_r$		71.1		ns	
Turn-off delay time	$t_{d(off)}$		103.9		ns	
Fall time	$t_f$		33.4		ns	

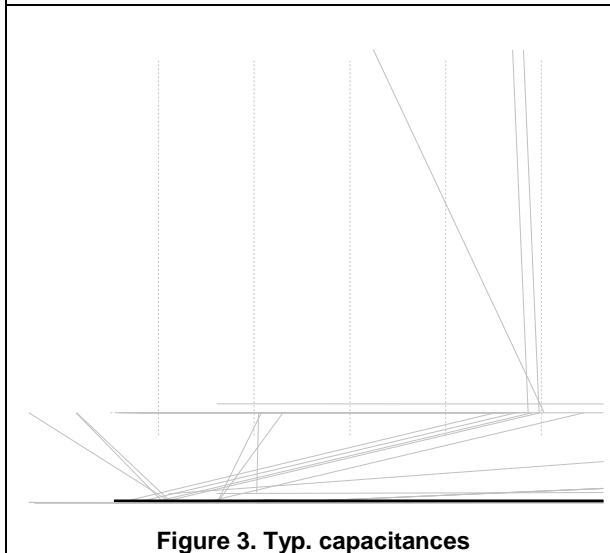
**Electrical Characteristics Diagrams**



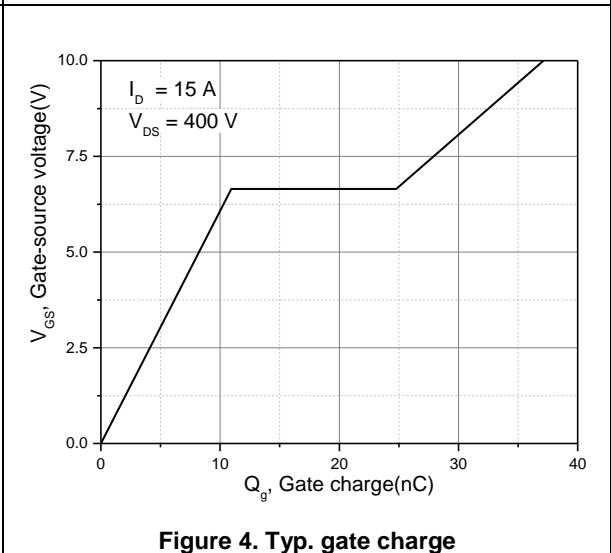
**Figure 1. Typ. output characteristics**



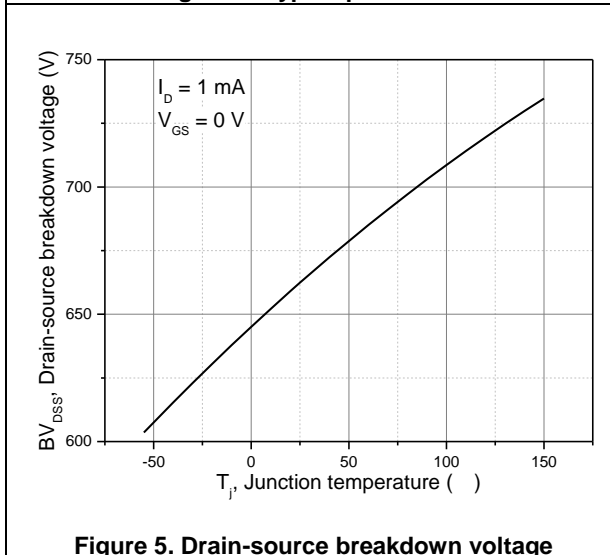
**Figure 2. Typ. transfer characteristics**



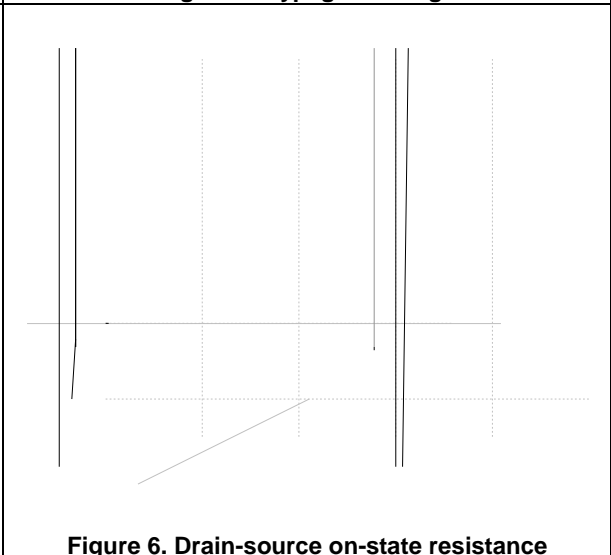
**Figure 3. Typ. capacitances**



**Figure 4. Typ. gate charge**



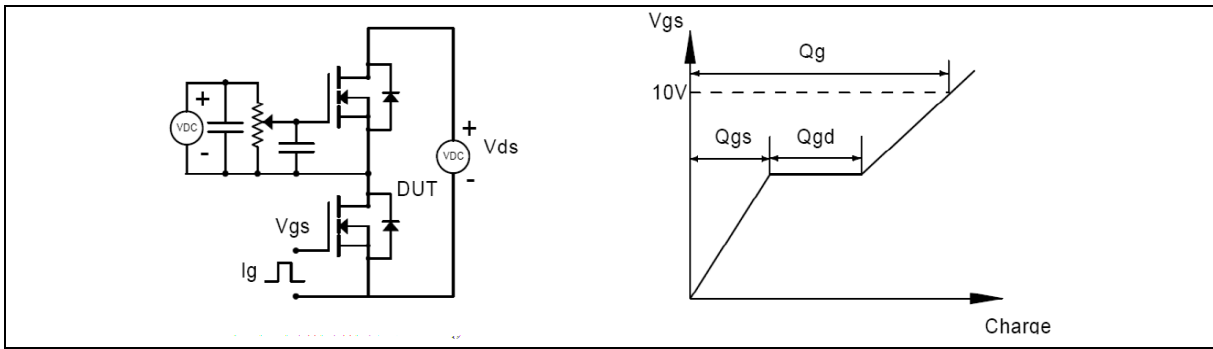
**Figure 5. Drain-source breakdown voltage**



**Figure 6. Drain-source on-state resistance**



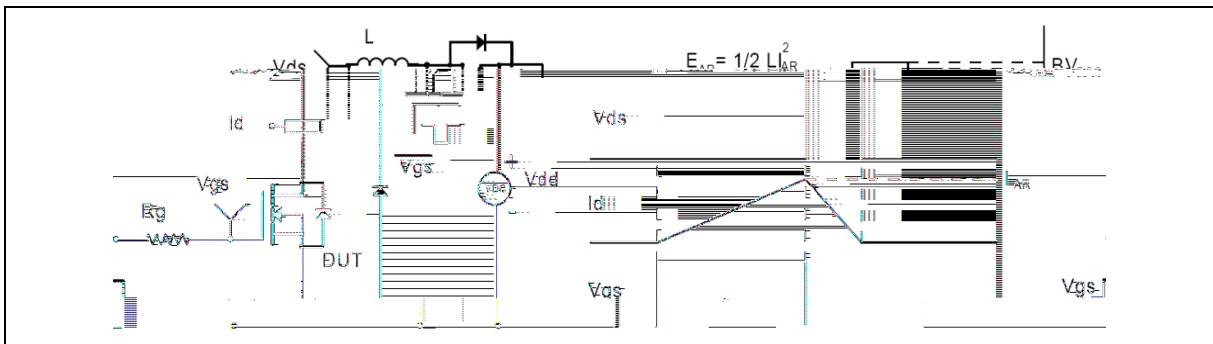
**Test circuits and waveforms**



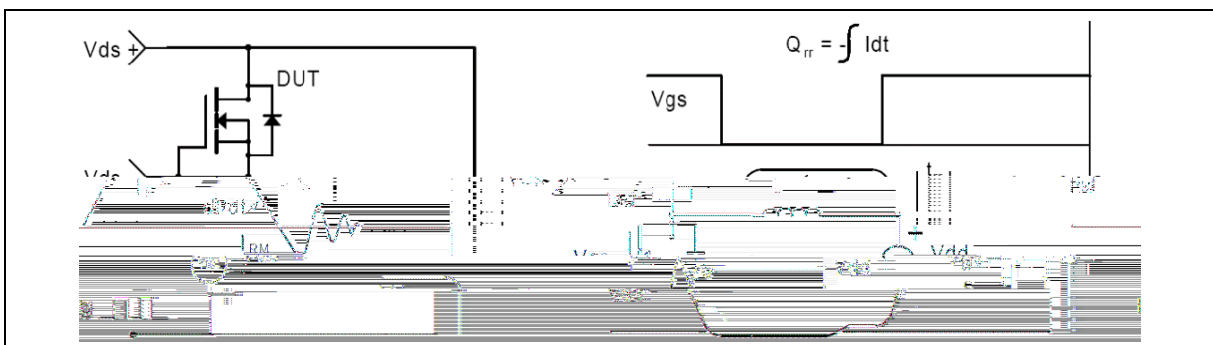
**Figure 1. Gate charge test circuit & waveform**



**Figure 2. Switching time test circuit & waveforms**



**Figure 3. Unclamped inductive switching (UIS) test circuit & waveforms**



**Figure 4. Diode reverse recovery test circuit & waveforms**

## Package Information

**Ordering Information**

Package Type	Units/ Tube	Tubes / Inner Box	Units/ Inner Box	Inner Boxes/ Carton Box	Units/ Carton Box
TO220F-P	50	20	1000	6	6000

**Product Information**

Product	Package	Pb Free	RoHS	Halogen Free
OSG60R108FZF	TO220F	yes	yes	yes

**Legal Disclaimer**

---

© Oriental Semiconductor Co.,Ltd. All Rights Reserved 